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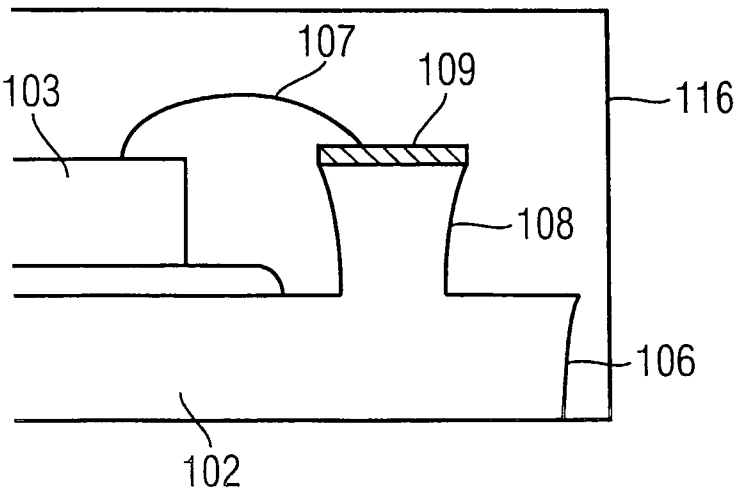
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(54) Title: CHIP SUPPORT OF A LEAD FRAME FOR AN INTEGRATED CIRCUIT PACKAGE



(57) Abstract: The central region of a lead frame (101, 201, 301, 401, 501, 601, 701, 801, 901, 1001, 1101, 1201), is selectively etched to leave upstanding portions (104, 204, 304, 404, 504, 604, 704, 804, 904, 1004, 1104, 1204). Subsequently, during the packaging process, an integrated circuit (3) is located on the central region of the lead frame, and wires (107) are formed between the upstanding portions of the lead frame and contacts (5) of the integrated circuit (3) which are to be grounded. Subsequently, the wires and upstanding portions of the lead frame are encased in resin (116). Since the upstanding portions of the lead frame are encased in resin, the resin (116) is mechanically locked to the lead frame. Furthermore, any delamination which occurs between the resin (116) and the lead frame cannot propagate easily up the sides of the upstanding portions as far as the wires (107), so the wires (107) are unlikely to be torn from the upstanding portions (104, 204, 304, 404, 504, 604, 704, 804, 904, 1004, 1104, 1204). Any adhesive which leaks from under the integrated circuit (3) when the integrated circuit (3) is mounted on the lead frame is most unlikely to cover any part of the upper surface of the upstanding portions.

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